GP2L09/GP2L24 GP2L26

Subminiature, High Sensitivity Photointerrupter

■ Features

1. Compact and thin
   GP2L09: Compact DIP, long lead type
   GP2L24: Compact DIP type
   GP2L26: Flat lead type
2. Optimum detection distance: 0.6 to 0.8mm
3. High sensitivity
   (I_C: MIN. 0.5mA at I_F = 4mA)
4. Visible light cut-off type

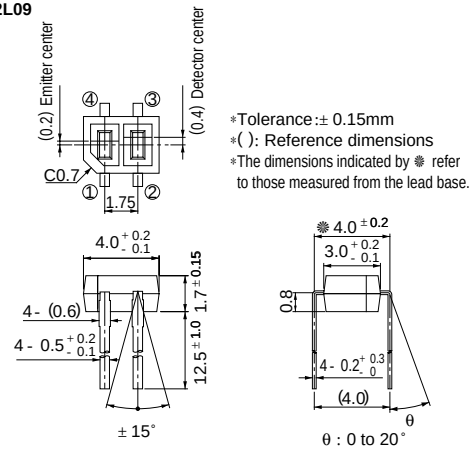
■ Applications

1. Cassette tape recorders, VCRs
2. Floppy disk drives
3. Various microcomputerized control equipment

■ Outline Dimensions

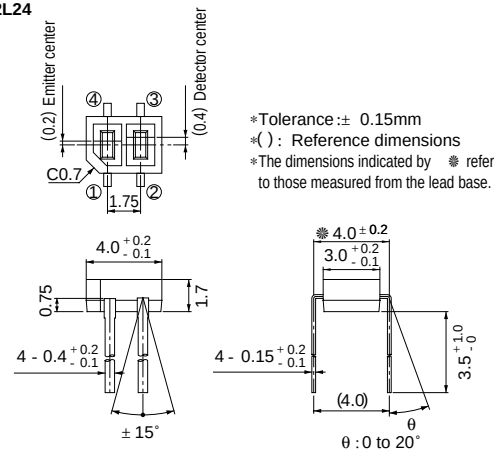
(Unit : mm)

GP2L09



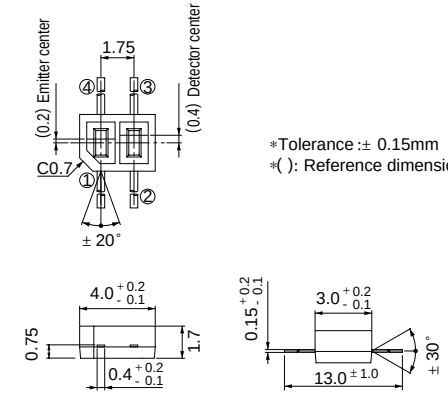
∗Tolerance : ± 0.15mm
∗( ): Reference dimensions
∗The dimensions indicated by ❁ refer to those measured from the lead base.

GP2L24



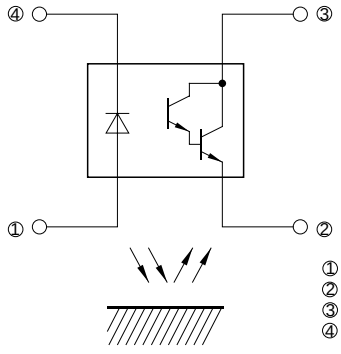
∗Tolerance : ± 0.15mm
∗( ): Reference dimensions
∗The dimensions indicated by ❁ refer to those measured from the lead base.

GP2L26



∗Tolerance : ± 0.15mm
∗( ): Reference dimensions

Internal connection diagram
(Common to 3 models)



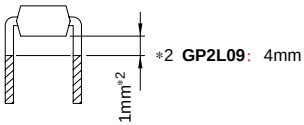
" In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that occur in equipment using any of SHARP's devices, shown in catalogs, data books, etc. Contact SHARP in order to obtain the latest version of the device specification sheets before using any SHARP's device."

■ Absolute Maximum Ratings (Ta = 25˚C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V_{CEO}	35	V
	Emitter-collector voltage	V_{ECO}	6	V
	Collector current	I_C	50	mA
	Collector power dissipation	P_C	75	mW
Total power dissipation		P_{tot}	100	mW
Operating temperature		T_{opr}	- 25 to + 85	˚C
Storage temperature		T_{stg}	- 40 to + 100	˚C
*1Soldering temperature		T_{sol}	260	˚C

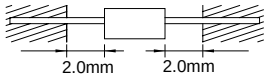
*1 Within 5 seconds (Soldering areas for each model are shown below.)

GP2L09, **GP2L24**
Soldering area
The hatched area more than 1mm*2 away from the lower edge of package as shown in the drawing below.



*2 **GP2L09**: 4mm

GP2L26
Soldering area
The hatched area more than 2.0mm away from the both edge of package as shown in the drawing below.



■ Electro-optical Characteristics (Ta = 25˚C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		I_F	I_F = 20mA	-	1.2	1.4	V
	Reverse current		I_R	V_R = 6V	-	-	10	μA
Output	Collector dark current		I_{CEO}	V_{CE} = 10V, I_F = 0	-	-	$1x\ 10^{-6}$	A
Transfer-characteristics	*3Collector current		I_C	V_{CE} = 2V, I_F = 4mA	0.5	3.0	15.0	mA
	Response time	Rise time	t_r	V_{CE} = 2V, I_C = 10mA R_L = 100Ω, d = 1mm	-	80	400	μs
		Fall time	t_f		-	70	400	μs
	*4Leak current		I_{LEAK}	I_F = 4mA, V_{CE} = 5V	-	-	5.0	μA

*3 The condition and arrangement of the reflective object are shown in the right drawing.
*4 Without reflective object

The ranking of collector current shall be classified into the following 6 ranks.
(**GP2L09**, **GP2L24**, **GP2L26**)

Rank	Collector current I_C (mA)
*5A	0.5 to 1.9
B	1.45 to 5.4
C	4.0 to 15.0
A or B	0.5 to 5.4
B or C	1.45 to 15.0
A, B or C	0.5 to 15.0

*5 **GP2L24** and **GP2L26** don't have A rank.

Test Condition for Collector Current

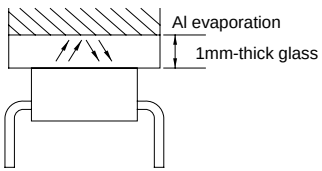


Fig. 1 Forward Current vs. Ambient Temperature

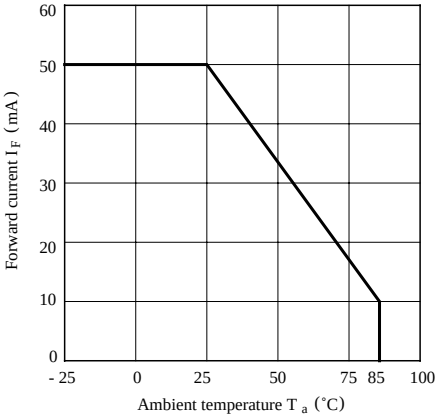


Fig. 2 Power Dissipation vs. Ambient Temperature

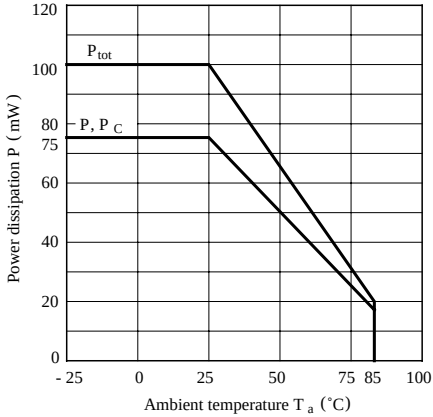


Fig. 3 Peak Forward Current vs. Duty Ratio

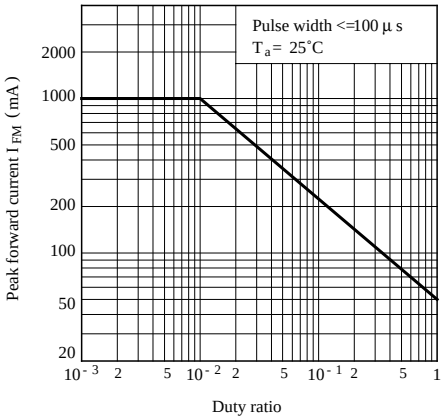


Fig. 4 Forward Current vs. Forward Voltage

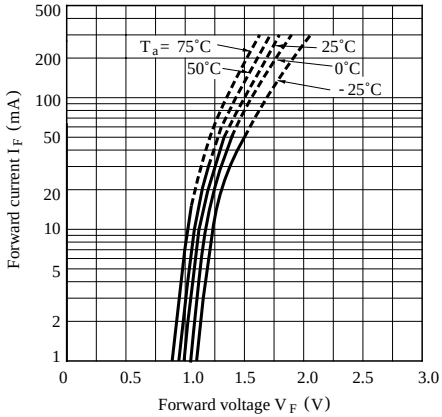


Fig. 5 Collector Current vs. Forward Current

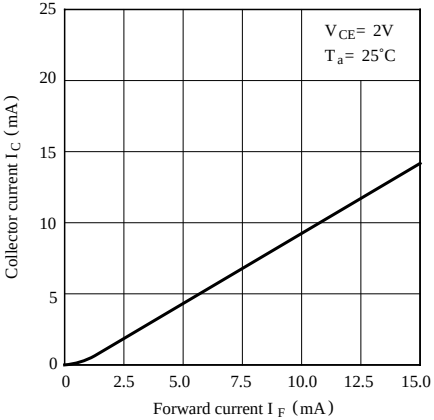


Fig. 6 Collector Current vs. Collector-emitter Voltage

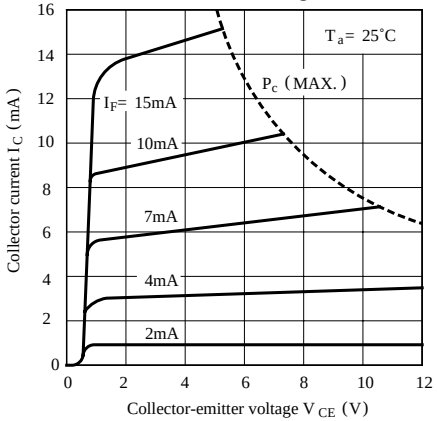


Fig. 7 Relative Collector Current vs. Ambient Temperature

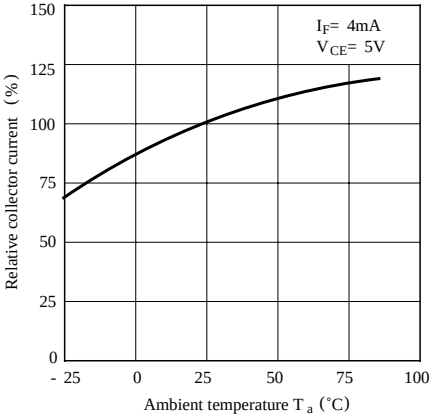


Fig. 8 Collector Dark Current vs. Ambient Temperature

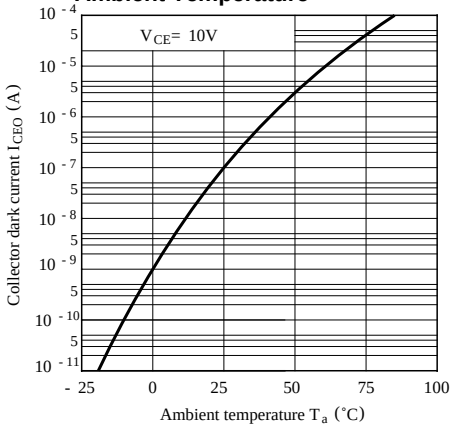


Fig. 9-a Response Time vs. Load Resistance (GP2L09)

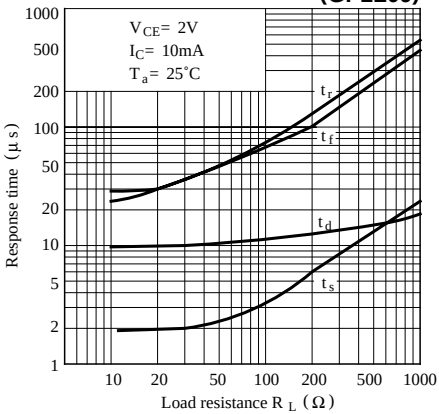
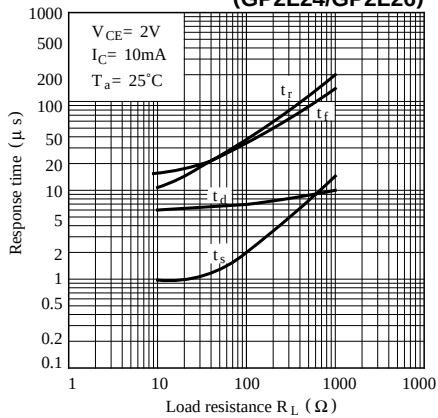


Fig. 9-b Response Time vs. Load Resistance (GP2L24/GP2L26)



Test Circuit for Response Time

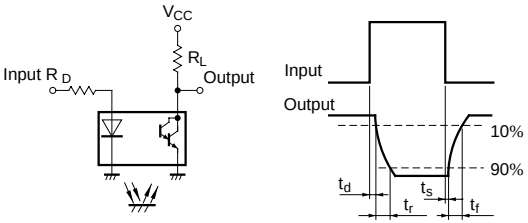


Fig.10 Relative Collector Current vs. Distance between Sensor and Al Evaporation Glass

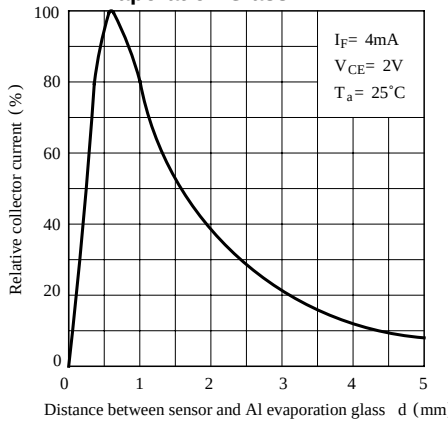


Fig.11 Relative Collector Current vs. Card Moving Distance (1)

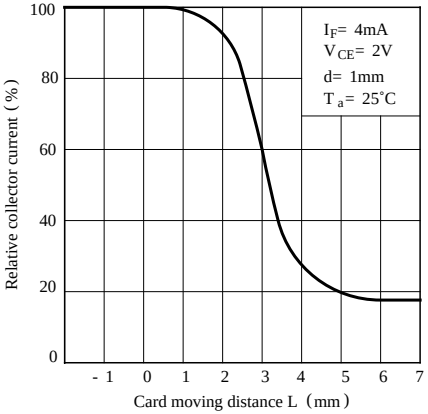
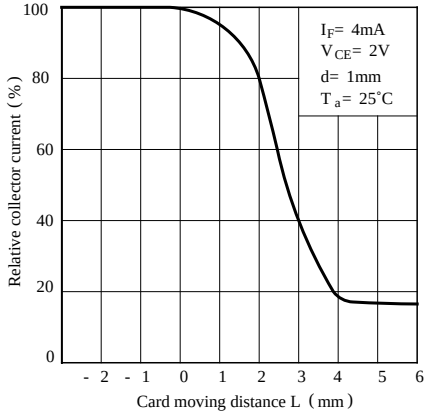


Fig.12 Relative Collector Current vs. Card Moving Distance (2)



Test Condition for Distance & Detecting Position Characteristics

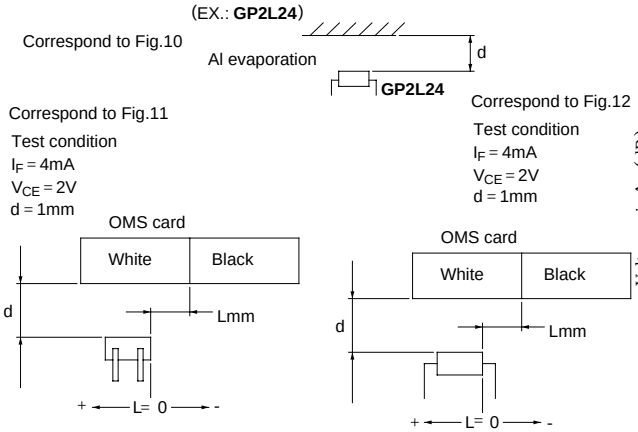


Fig.13 Frequency Response (GP2L09)

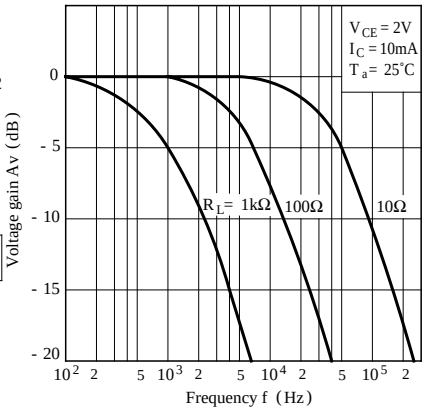


Fig.14 Frequency Response (GP2L24/ GP2L26)

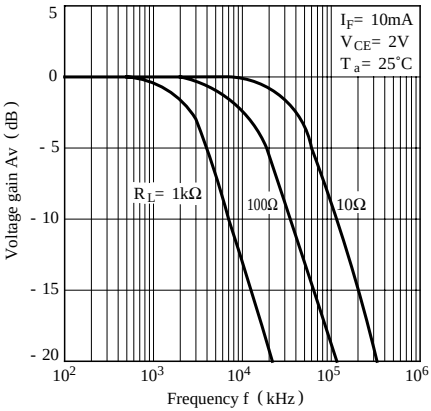
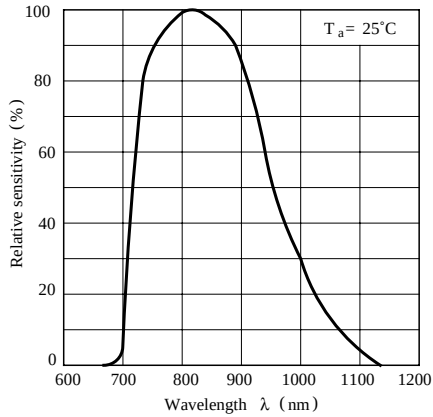


Fig.15 Spectral Sensitivity (Detecting Side)



■ Precautions for Use

(1) In order to stabilize power supply line, connect a by-pass capacitor of more than 0.01 μF between Vcc and GND near the device.

(2) In this product, the PWB is fixed with a resin cover, and cleaning solvent may remain inside the case; therefore, dip cleaning or ultrasonic cleaning are prohibited.

(3) Remove dust or stains, using an air blower or a soft cloth moistened in cleaning solvent. However, do not perform the above cleaning using a soft cloth with cleaning solvent in the marking portion.
In this case, use only the following type of cleaning solvent used for wiping off:
Ethyl alcohol, Methyl alcohol, Isopropyl alcohol, Freon TE, Freon TF, Diflon solvent S3-E
When the cleaning solvents except for specified materials are used, please consult us.

(4) As for other general cautions, refer to the chapter " Precautions for Use ".